

ABSTRACT OF THE DISCLOSURE

A linear image sensor chip is manufactured by forming an image pickup section, peripheral circuit sections, a plurality of bonding pads, and a light-suppressing layer on a semiconductor substrate having an elongated shape. In

- 5 this case, each of the bonding pads is formed outer than photodiode groups in the image pickup section along a longitudinal direction of the semiconductor substrate. Even if the dynamic range of an image reader utilizing such a linear image sensor chip is broadened, it is possible to suppress generation of noises without lowering the sensitivity.